

LTCC Multi Layer Chip Balun- 1005 (0402) size

- RFBLN10051G9D0T
- For LTE B34/B35 Application

FEATURES

- Miniature footprint: 1.0 X 0.5X 0.4 mm³
- Low Insertion Loss
- Low in-band amplitude and phase imbalance enhances system performance
- LTCC process

APPLICATIONS

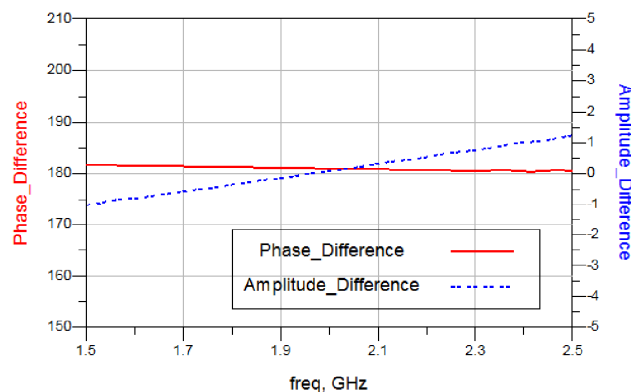
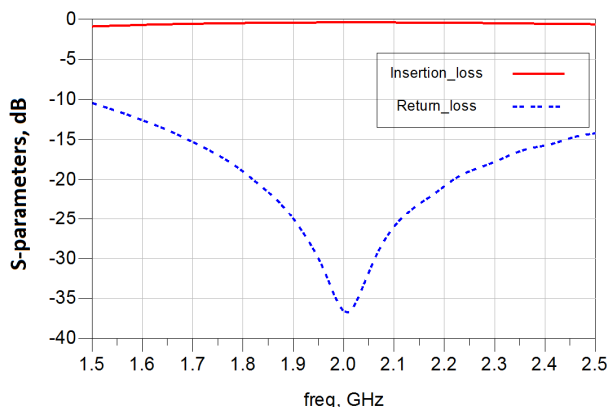
- LTE B34/B35 applications

ELECTRICAL CHARACTERISTICS

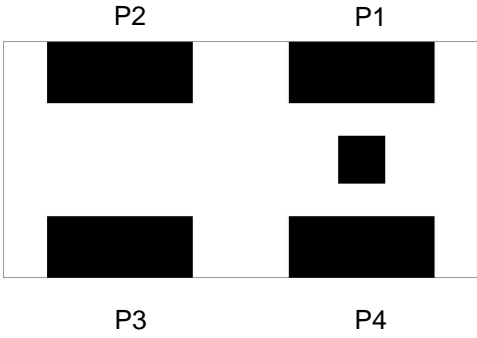
Item	Specification
Frequency Range	1850~2020 MHz
VSWR	2.0
Insertion Loss	0.65 dB max. at +25°C 0.75 dB max. at -40~ +85°C
Unbalanced Impedance	50Ω
Balanced Impedance	100Ω
Phase Difference	180°± 10°
Amplitude Difference	2.0 dB max.
Taping Quantity	: 4000pcs per 7" reel
Operating Temperature Range	: -40~ +85°C
Storage Temperature Range	: -10~ +40°C
Humidity	: 30 to 70% relative humidity

TYPICAL ELECTRICAL PERFORMANCE

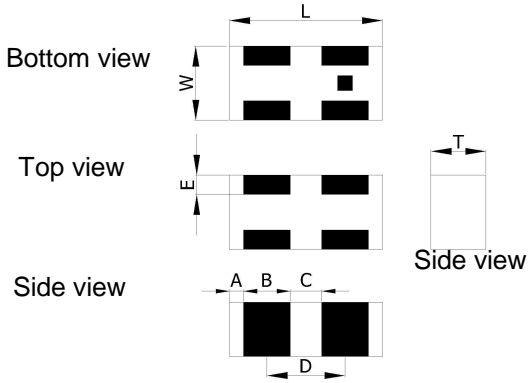
S-Parameter



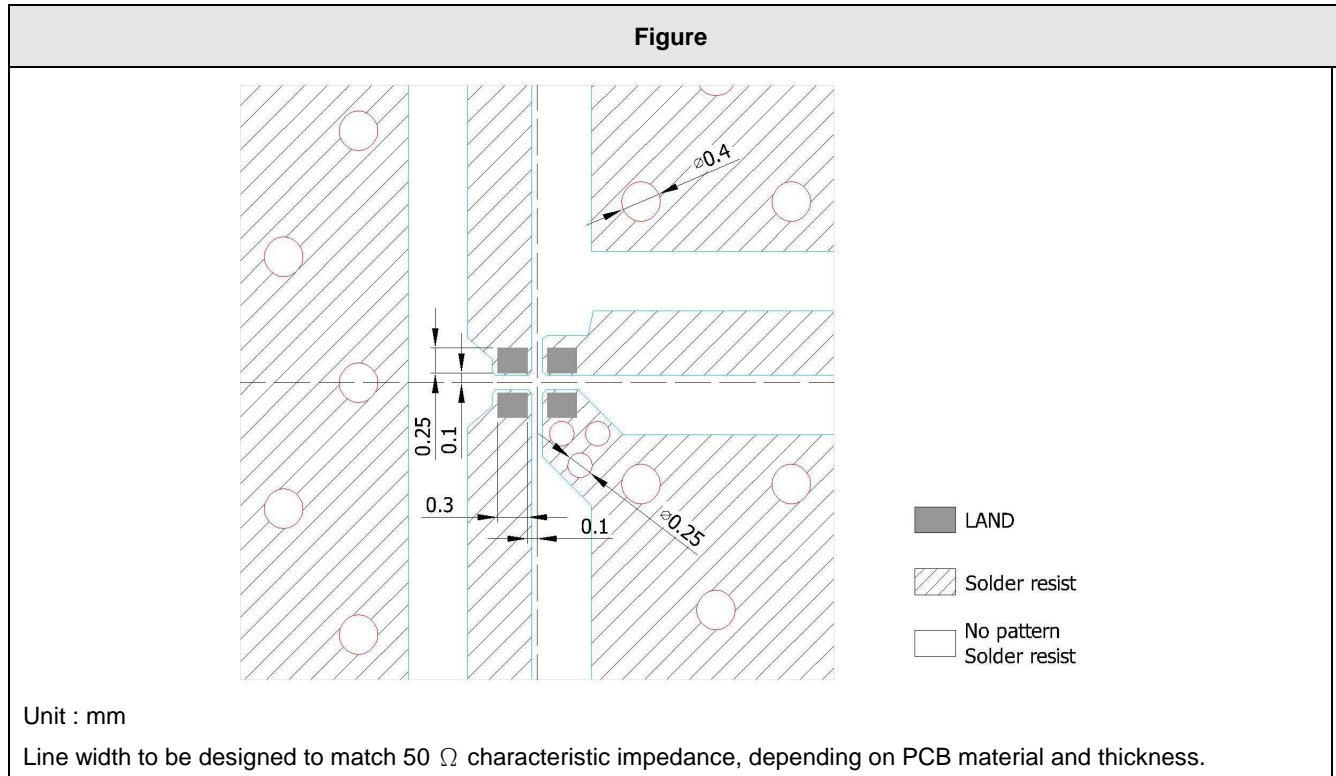
CONSTRUCTION

Figure	PIN	Connection
Top view 	1	Unbalanced port
	2	Balanced port
	3	Balanced port
	4	GND

DIMENSIONS

Figure	Symbol	Dimension (mm)
Bottom view Top view Side view 	L	1.00 ± 0.10
	W	0.50 ± 0.10
	T	0.40 ± 0.10
	A	0.10 ± 0.10
	B	0.30 ± 0.10
	C	0.20 ± 0.10
	D	0.50 ± 0.10
E	0.125 ± 0.10	

SOLDER LAND PATTERN



CONTACT INFORMATION

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Specification subject to change without prior notice